FAIRCHILD
SEMICONDUCTOR TM

August 1998

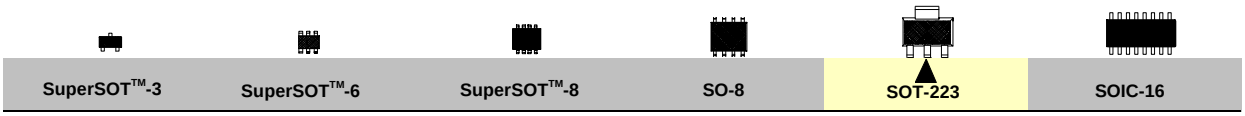
NDT3055L
N-Channel Logic Level Enhancement Mode Field Effect Transistor

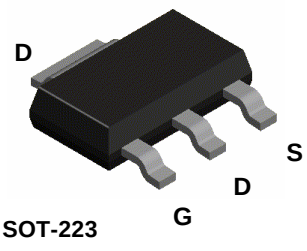
General Description

These logic level N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance and provide superior switching performance, and withstand high energy pulse in the avalanche and commutation modes. These devices are particularly suited for low voltage applications such as DC motor control and DC/DC conversion where fast switching, low in-line power loss, and resistance to transients are needed.

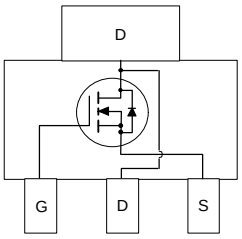
Features

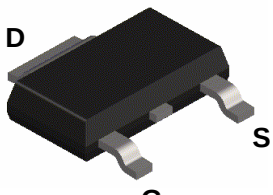
- 4 A, 60 V. $R_{DS(ON)}$ = 0.100 Ω @ V_{GS} = 10 V,
  $R_{DS(ON)}$ = 0.120 Ω @ V_{GS} = 4.5 V.
- Low drive requirements allowing operation directly from logic drivers. $V_{GS(TH)}$ < 2V.
- High density cell design for extremely low $R_{DS(ON)}$.
- High power and current handling capability in a widely used surface mount package.



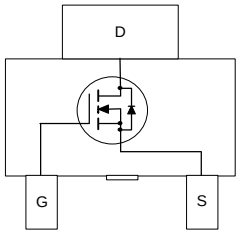


SOT-223





SOT-223*
(J23Z)



Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	NDT3055L	Units
V_{DSS}	Drain-Source Voltage	60	V
V_{GSS}	Gate-Source Voltage - Continuous	±20	V
I_D	Maximum Drain Current - Continuous (Note 1a)	4	A
	- Pulsed	25	
P_D	Maximum Power Dissipation (Note 1a)	3	W
	(Note 1b)	1.3	
	(Note 1c)	1.1	
T_J,T_{STG}	Operating and Storage Temperature Range	-65 to 150	°C
THERMAL CHARACTERISTICS			
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	42	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	12	°C/W

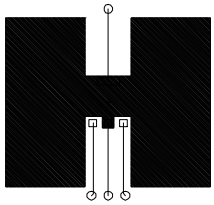
* Order option J23Z for cropped center drain lead.

Electrical Characteristics (T_A = 25 °C unless otherwise noted)

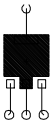
Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 µA	60			V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	I_D = 250 µA, Referenced to 25 °C		55		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 60 V, V_{GS} = 0 V			1	µA
		T_J =125°C			50	µA
I_{GSSF}	Gate - Body Leakage, Forward	V_{GS} = 20 V, V_{DS} = 0 V			100	nA
I_{GSSR}	Gate - Body Leakage, Reverse	V_{GS} = -20 V, V_{DS} = 0 V			-100	nA
ON CHARACTERISTICS (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250 µA	1	1.6	2	V
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Temp. Coefficient	I_D = 250 µA, Referenced to 25 °C		-4		mV /°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS} = 10 V, I_D = 4 A		0.07	0.1	Ω
		T_J =125°C		0.125	0.18	
		V_{GS} = 4.5 V, I_D = 3.7 A		0.103	0.12	
$I_{D(ON)}$	On-State Drain Current	V_{GS} = 5 , V_{DS} = 10 V	10			A
g_{FS}	Forward Transconductance	V_{DS} = 5 V, I_D = 4 A		7		S
DYNAMIC CHARACTERISTICS						
C_{iss}	Input Capacitance	V_{DS} = 25, V_{GS} = 0 V, f = 1.0 MHz		345		pF
C_{oss}	Output Capacitance			110		pF
C_{rss}	Reverse Transfer Capacitance			30		pF
SWITCHING CHARACTERISTICS (Note 2)						
$t_{D(on)}$	Turn - On Delay Time	V_{DD} = 25, I_D = 1 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		5	20	ns
t_r	Turn - On Rise Time			7.5	20	ns
$t_{D(off)}$	Turn - Off Delay Time			20	50	ns
t_f	Turn - Off Fall Time			7	20	ns
Q_g	Total Gate Charge	V_{DS} = 40 V, I_D = 4 A, V_{GS} = 10 V		13	20	nC
Q_{gs}	Gate-Source Charge			1.7		nC
Q_{gd}	Gate-Drain Charge			3.2		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
I_S	Maximum Continuous Drain-Source Diode Forward Current				2.5	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 2.5 A (Note 2)		0.8	1.2	V

Notes:

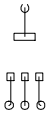
1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 42°C/W when mounted on a 1 in^2 pad of 2oz Cu.



b. 95°C/W when mounted on a 0.066 in^2 pad of 2oz Cu.



c. 110°C/W when mounted on a 0.00123 in^2 pad of 2oz Cu.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%

Typical Electrical Characteristics

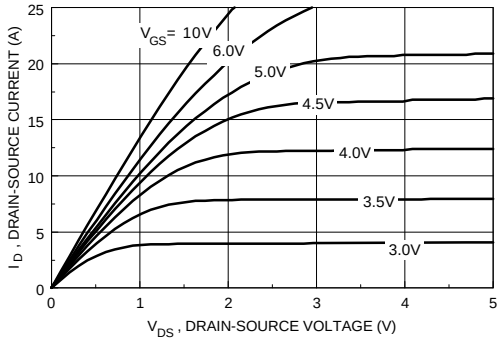


Figure 1. On-Region Characteristics.

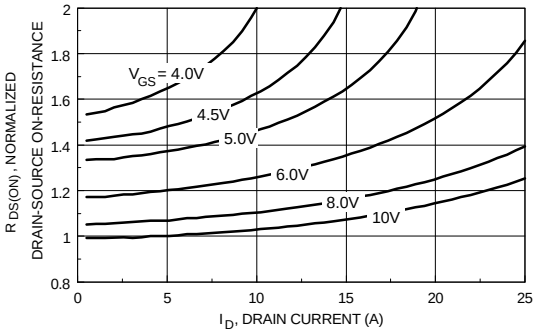


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

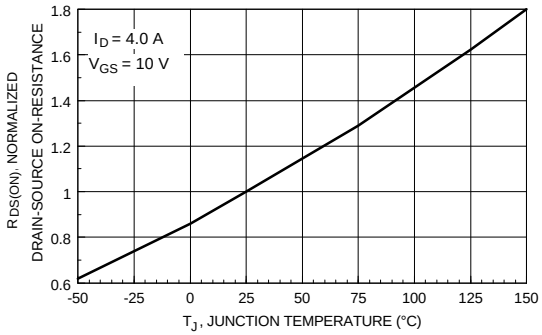


Figure 3. On-Resistance Variation with Temperature.

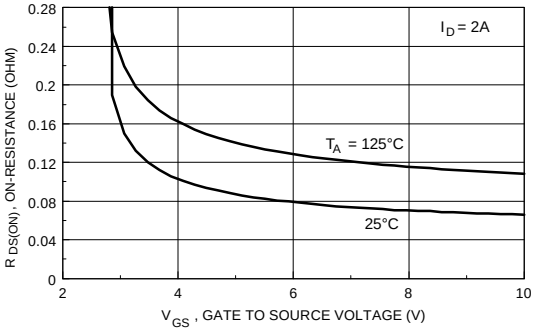


Figure 4. On-Resistance Variation with Gate-to- Source Voltage.

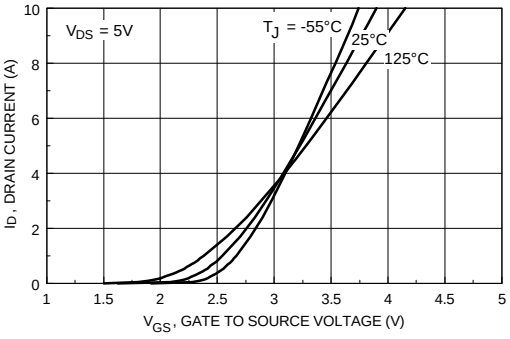


Figure 5. Transfer Characteristics.

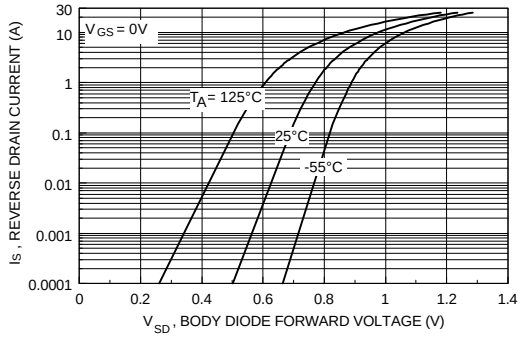


Figure 6. Body Diode Forward Voltage Variation with Current and Temperature.

Typical Electrical Characteristics (continued)

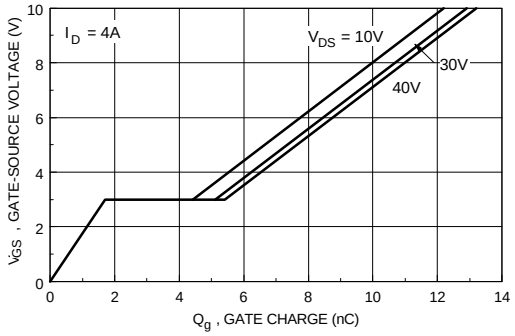


Figure 7. Gate Charge Characteristics.

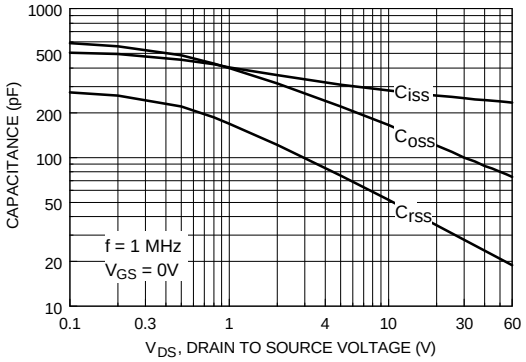


Figure 8. Capacitance Characteristics.

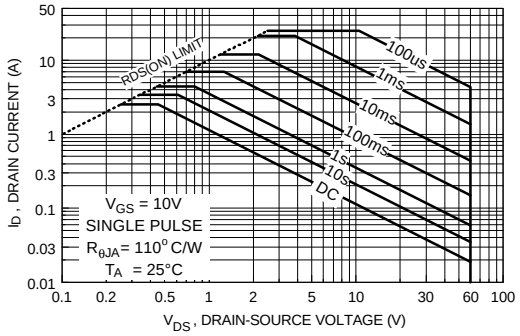


Figure 9. Maximum Safe Operating Area.

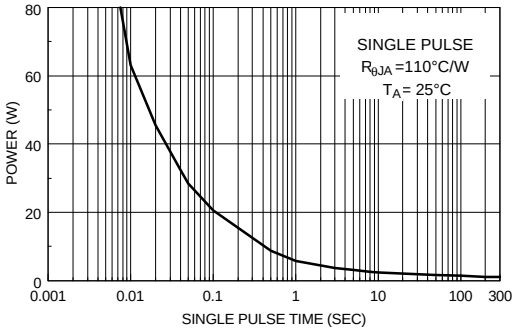


Figure 10. Single Pulse Maximum Power Dissipation.

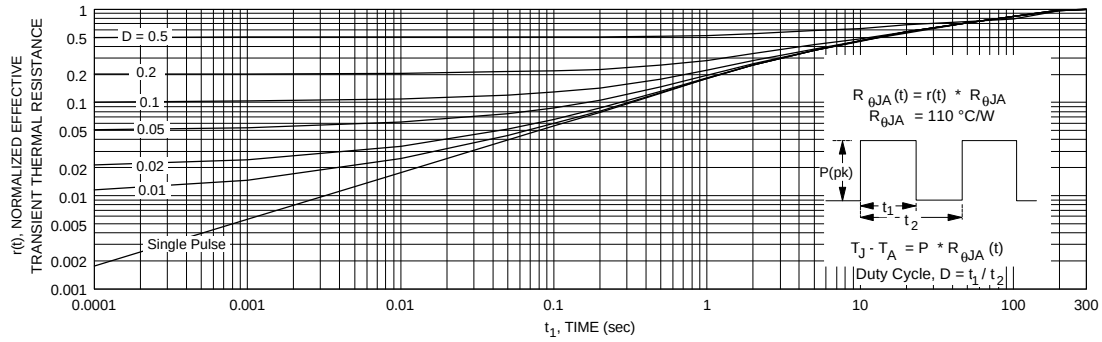


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in note 1c.
Transient thermal response will change depending on the circuit board design.

SOT-223 Tape and Reel Data and Package Dimensions

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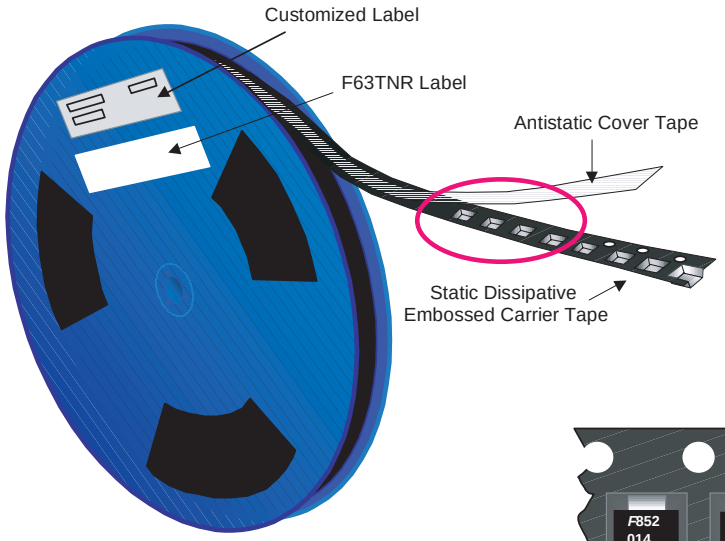
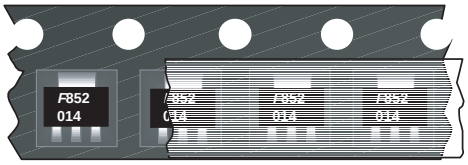
SOT-223 Packaging Configuration: Figure 1.0



Packaging Description:

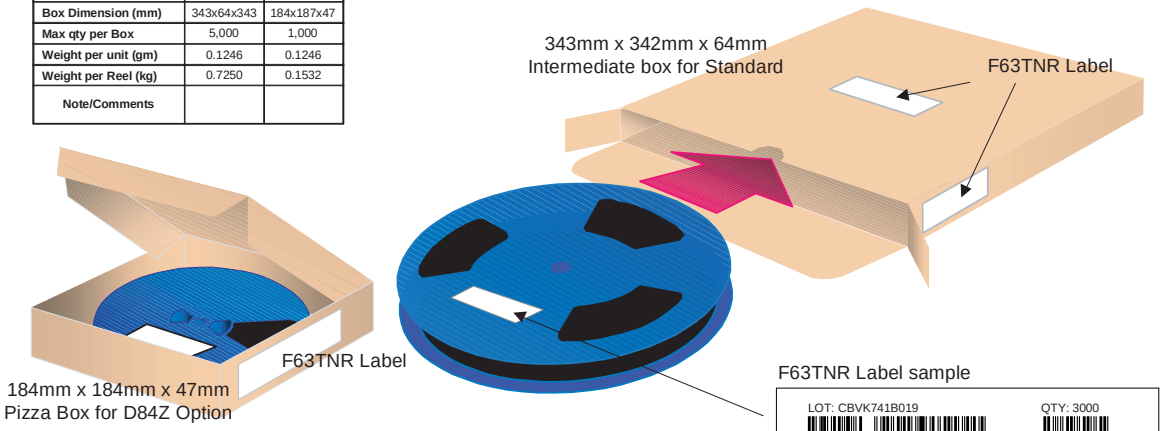
SOT-223 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 330cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 500 units per 7" or 177cm diameter reel. This and some other options are further described in the Packaging Information table.

These full reels are individually barcode labeled and placed inside a standard intermediate box (illustrated in figure 1.0) made of recyclable corrugated brown paper. One box contains two reels maximum. And these boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.

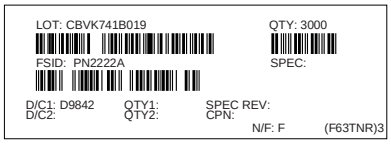


SOT-223 Unit Orientation

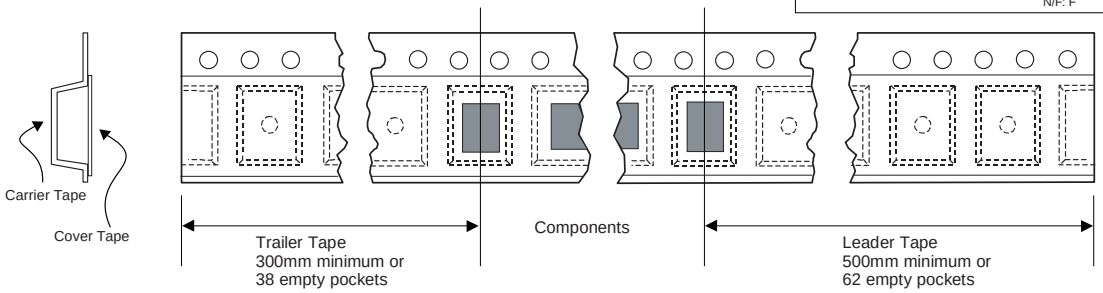
SOT-223 Packaging Information		
Packaging Option	Standard (no flow code)	D84Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	2,500	500
Reel Size	13" Dia	7" Dia
Box Dimension (mm)	343x64x343	184x187x47
Max qty per Box	5,000	1,000
Weight per unit (gm)	0.1246	0.1246
Weight per Reel (kg)	0.7250	0.1532
Note/Comments		



F63TNR Label sample

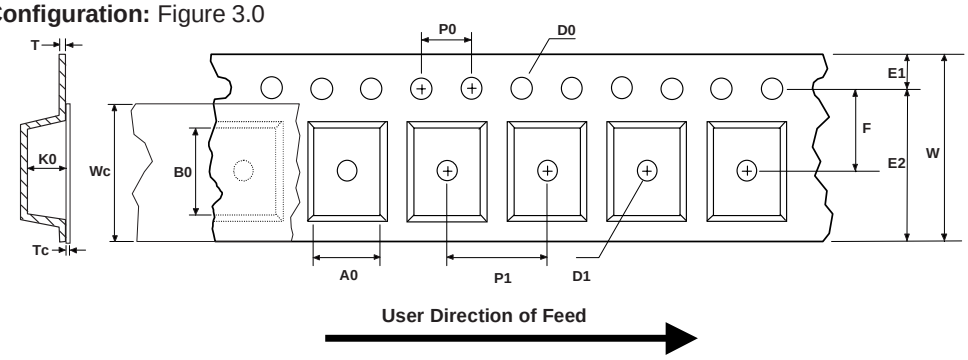


SOT-223 Tape Leader and Trailer Configuration: Figure 2.0



SOT-223 Tape and Reel Data and Package Dimensions, continued

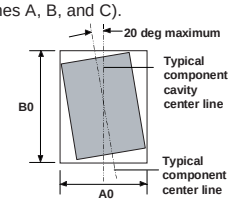
SOT-223 Embossed Carrier Tape
Configuration: Figure 3.0



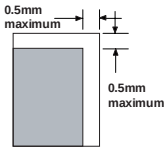
Dimensions are in millimeter														
Pkg type	**A0**	**B0**	**W**	**D0**	**D1**	**E1**	**E2**	**F**	**P1**	**P0**	**K0**	**T**	**Wc**	**Tc**
SOT-223 (12mm)	6.83 +/-0.10	7.42 +/-0.10	12.0 +/-0.3	1.55 +/-0.05	1.50 +/-0.10	1.75 +/-0.10	10.25 min	5.50 +/-0.05	8.0 +/-0.1	4.0 +/-0.1	1.88 +/-0.10	0.292 +/- 0.0130	9.5 +/-0.025	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).

Sketch A (Side or Front Sectional View)
Component Rotation

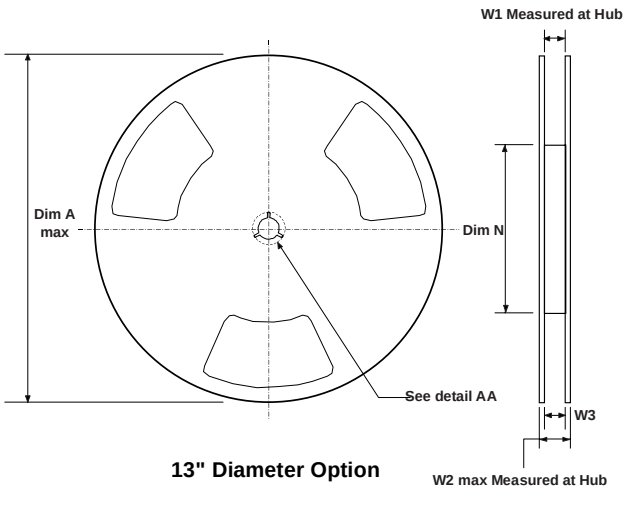


Sketch B (Top View)
Component Rotation

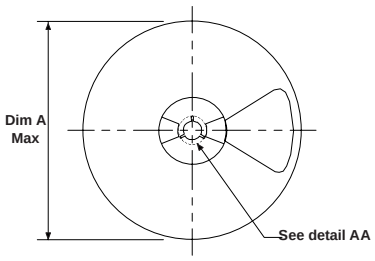


Sketch C (Top View)
Component lateral movement

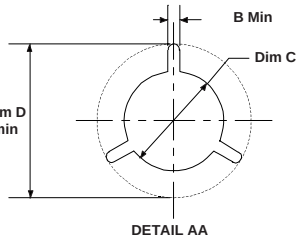
SOT-223 Reel Configuration: Figure 4.0



13" Diameter Option



7" Diameter Option

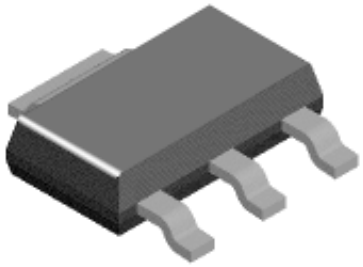


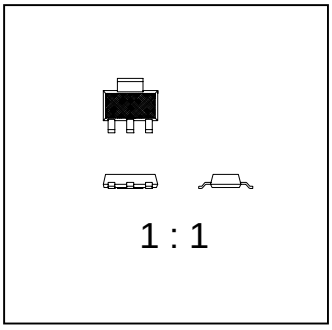
DETAIL AA

Dimensions are in inches and millimeters									
Tape Size	**Reel Option**	**Dim A**	**Dim B**	**Dim C**	**Dim D**	**Dim N**	**Dim W1**	**Dim W2**	**Dim W3 (LSL-USL)**
12mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	5.906 150	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 – 0.606 11.9 – 15.4
12mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	7.00 178	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 – 0.606 11.9 – 15.4

SOT-223 Tape and Reel Data and Package Dimensions, continued

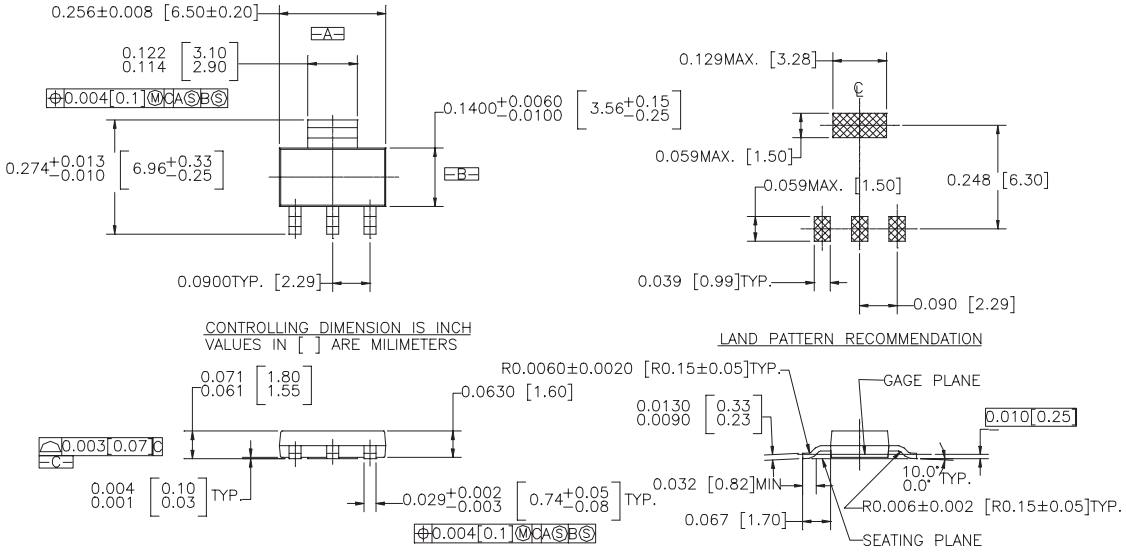
SOT-223 (FS PKG Code 47)





Scale 1:1 on letter size paper

Part Weight per unit (gram): 0.1246



NOTES : UNLESS OTHERWISE SPECIFIED
1. STANDARD LEAD FINISH TO BE 150 MICROINCHES/ 3.81 MICROMETERS MINIMUM TIN/LEAD (SOLDER) ON COPPER.
2. REFERENCE JEDEC REGISTRATION TO−261, VARIATION AA, ISSUE A, DATED JAN 1990

SOT223, 4 LEADS

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SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
TinyLogic™
UHC™
VCX™

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.